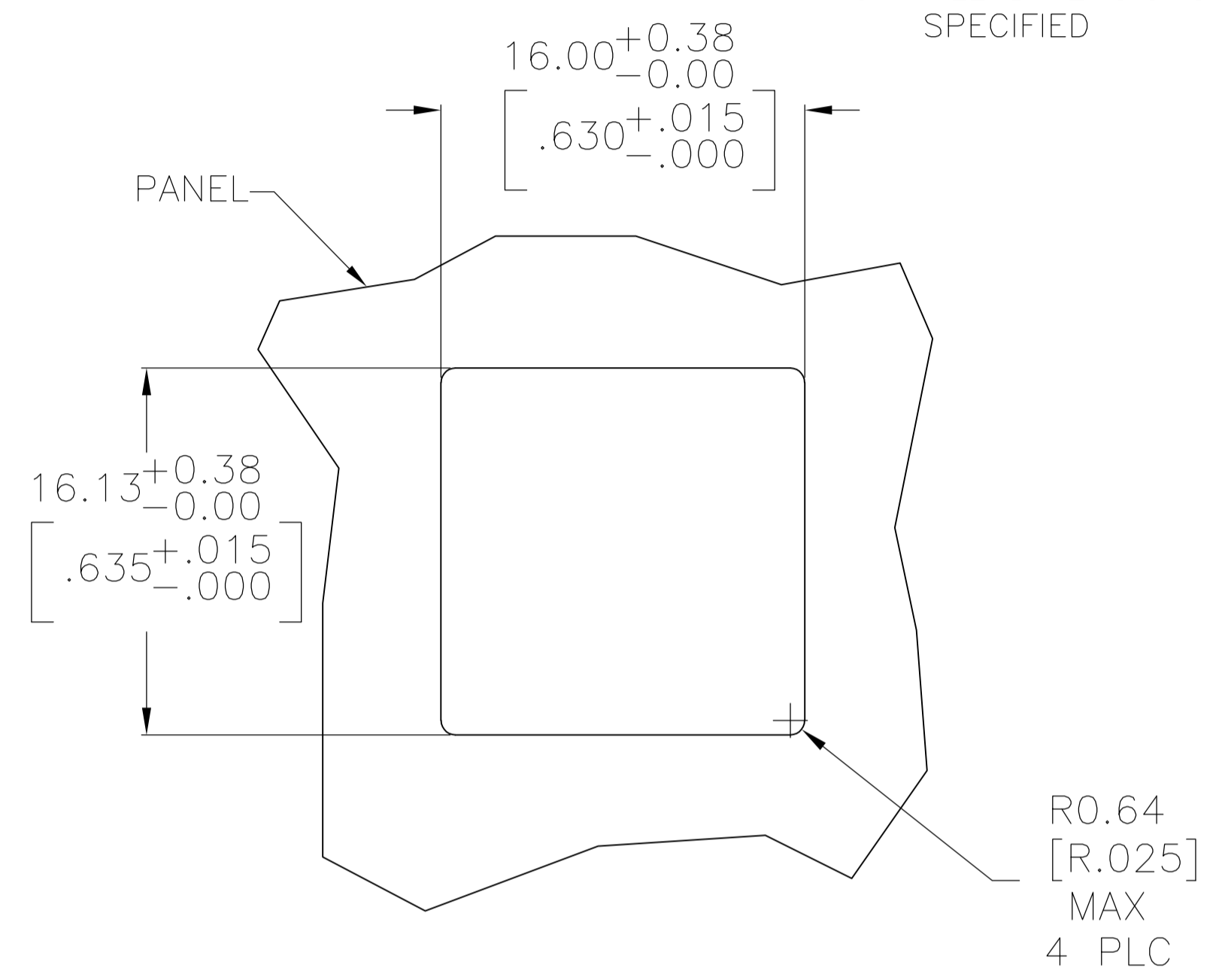
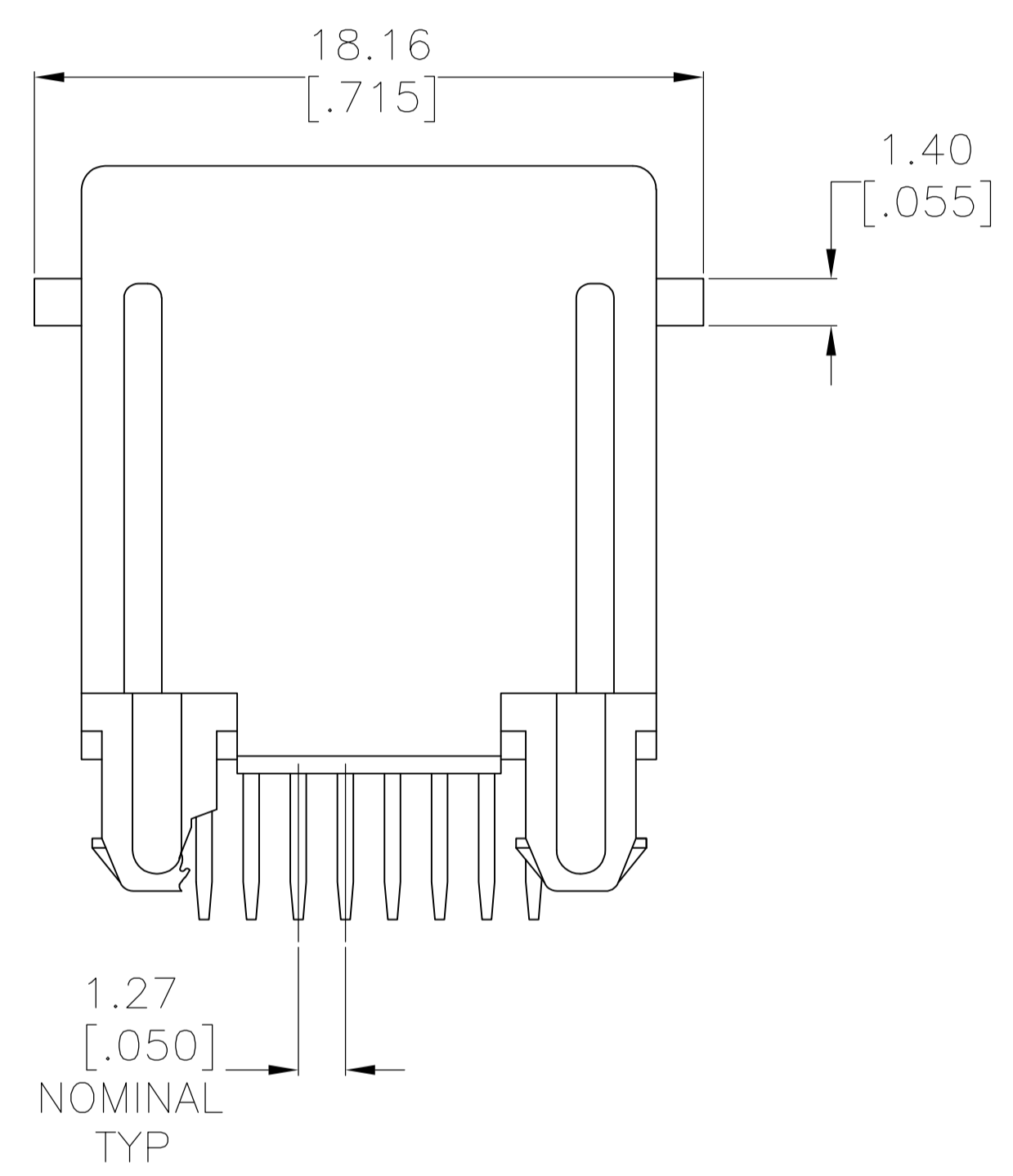
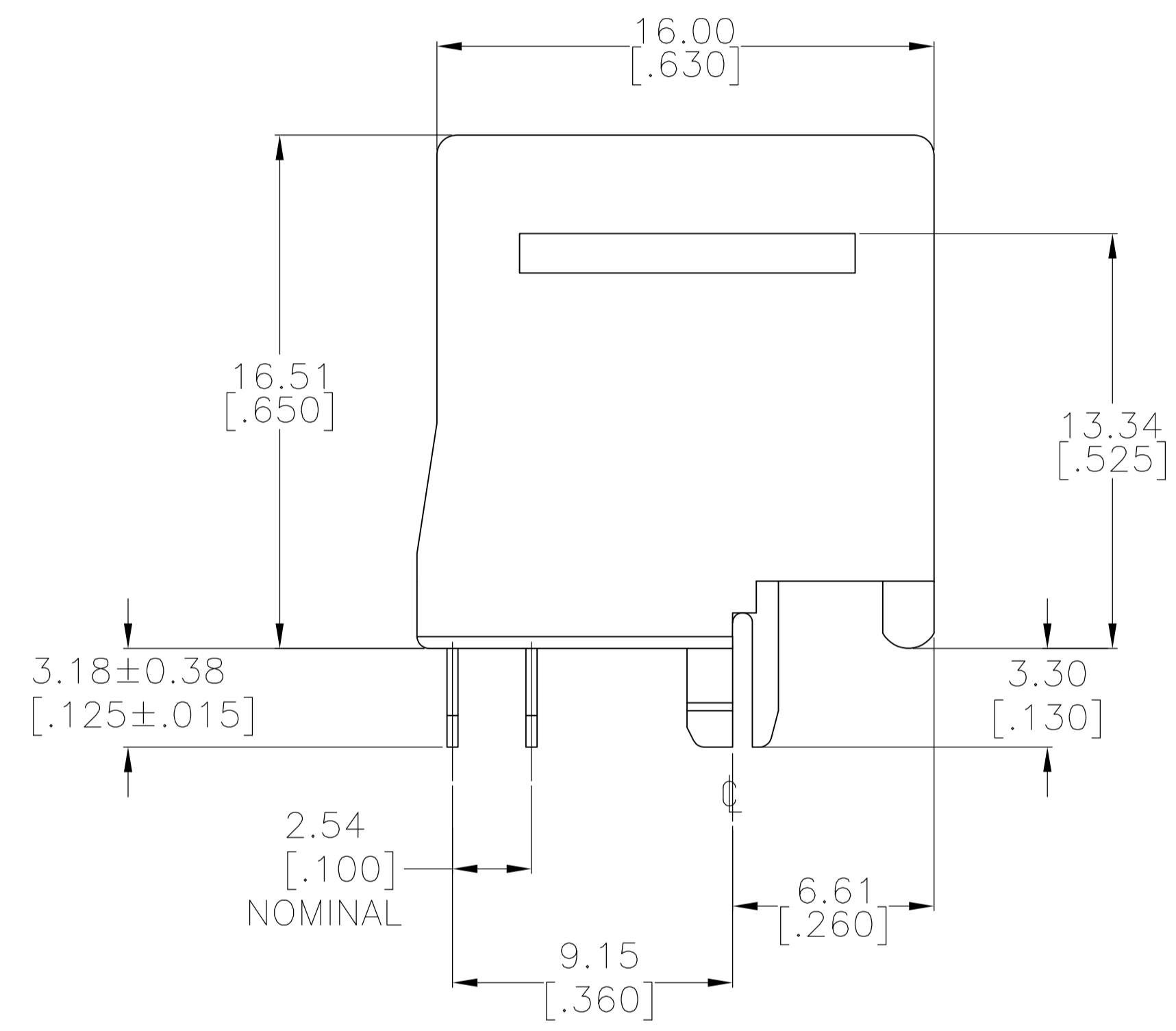
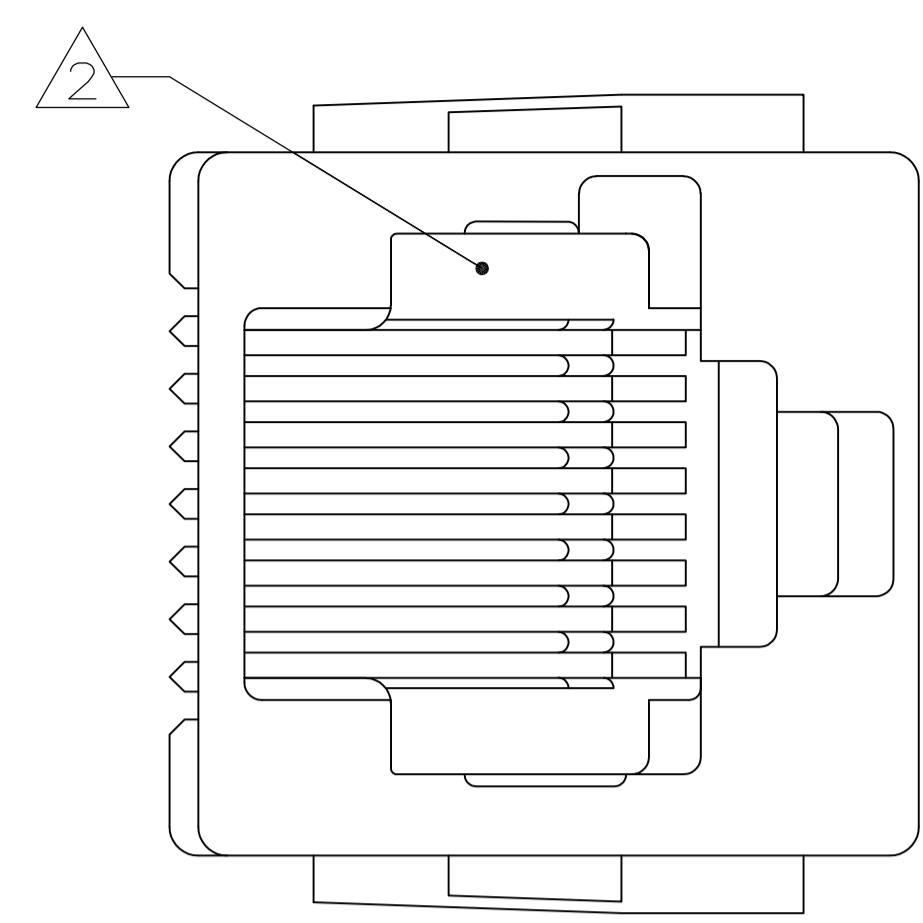
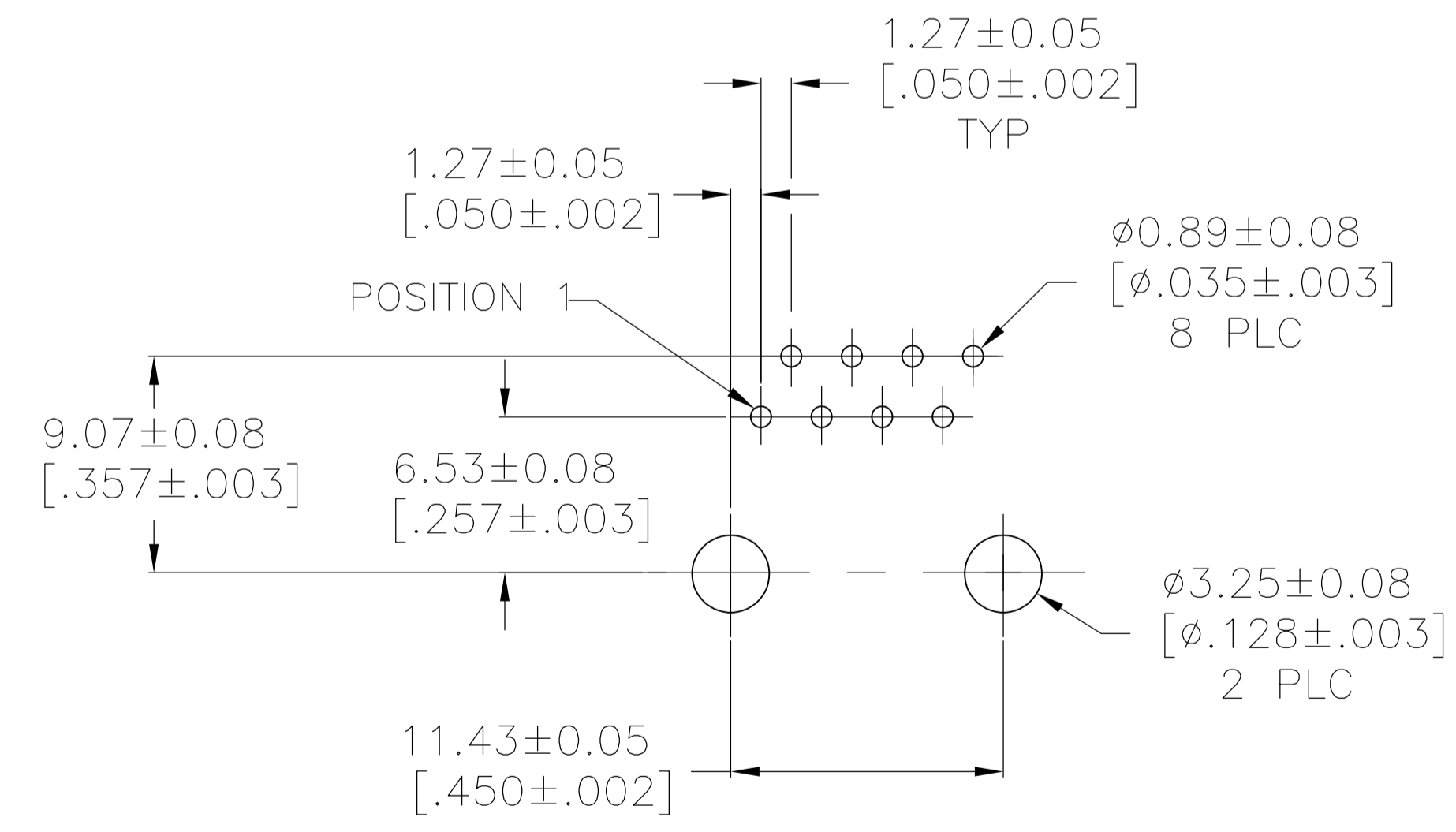
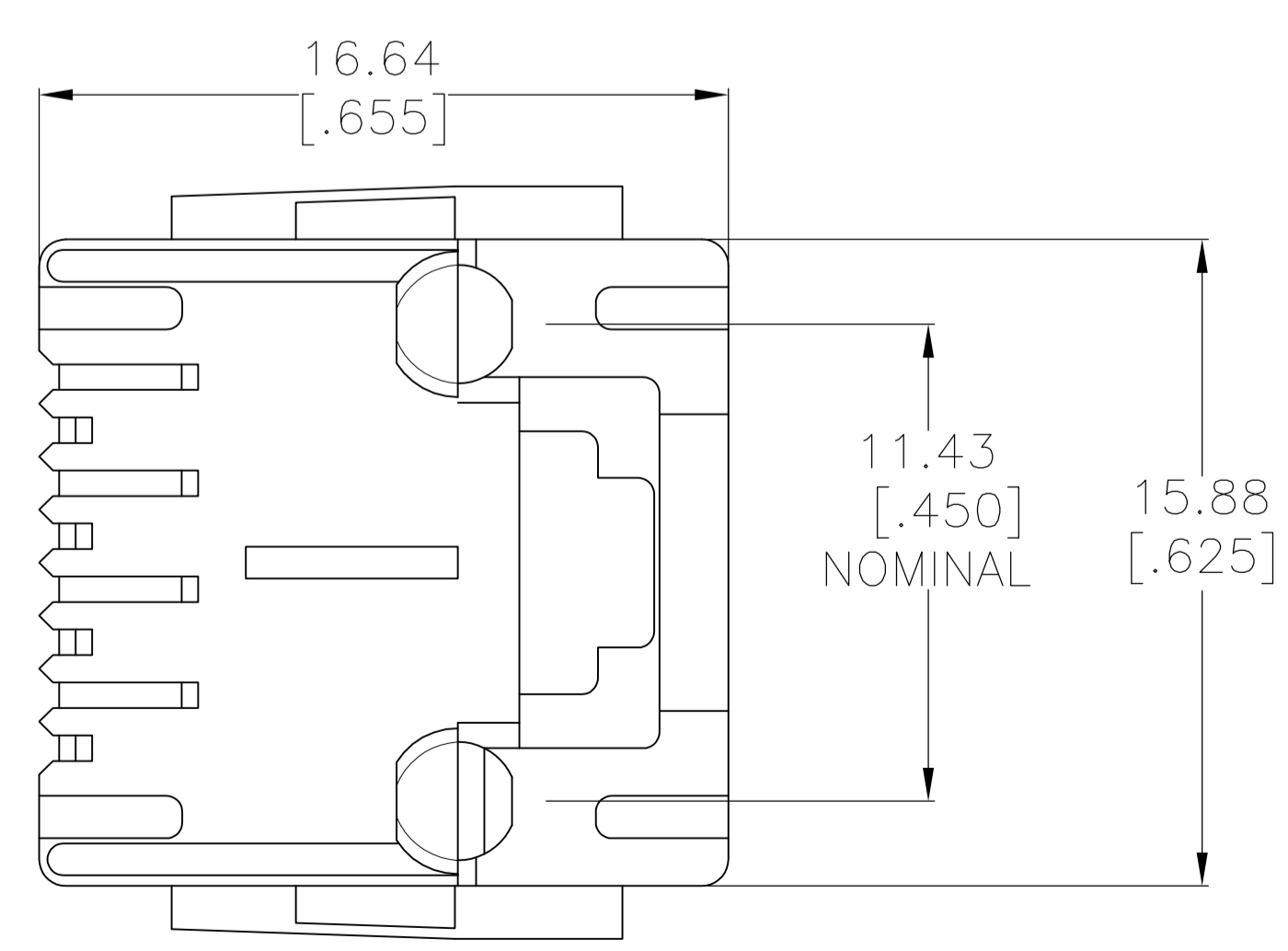


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
C1	REVISED PER ECO-11-005033		23MAR11	RK	HMR		



RECOMMENDED PANEL CUTOUT SCALE 4:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SCALE 4:1

- MATERIAL: HOUSING: PBT POLYESTER, COLOR: BLACK
TERMINAL: 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] MIN THICK NICKEL UNDERPLATE
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED

5520260-4
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - 06/JUN/2005	STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN - 06/JUN/2005	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPV S. FLICKINGER - 06/JUN/2005	MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, KEYED, FLANGELESS, WITH PANEL STOPS	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC	108-1163	
2 PLC ± -	3 PLC ± -	APPLICATION SPEC	114-2048	
4 PLC ± -	ANGLES ± -	SIZE CAGE CODE DRAWING NO	A1 00779 5520260	
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	CUSTOMER DRAWING SCALE 6:1 SHEET 1 OF 1 REV C1	